

# MA2C029W

## Silicon epitaxial planar type

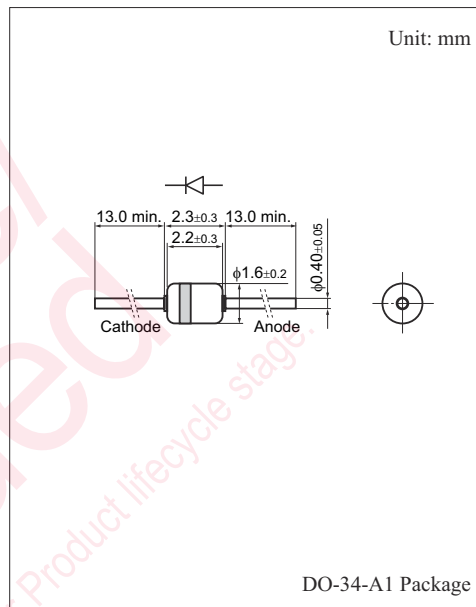
For reduced voltage and temperature compensation

### ■ Features

- High reliability achieved through combination of a planar type chip and glass sealing structure
- Easy mounting because of employing DO-35 (DHD) envelope
- Extremely small reverse current  $I_R$
- Large power dissipation  $P_D$
- Wide forward voltage  $V_F$  range

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	6	V
Peak forward current	$I_{FM}$	100	mA
Power dissipation	$P_D$	150	mW
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$



### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}^{*1}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward current	$V_{F1}$	$I_R = 10 \mu\text{A}$	0.77			V
	$V_{F2}$	$I_F = 3 \text{ mA}$		*2		
Reverse current	$I_R$	$V_R = 6 \text{ V}$			1.0	$\mu\text{A}$
Temperature coefficient of forward voltage *3	$-\Delta V_F / V_T$	$I_F = 3 \text{ mA}$		4.6		$\text{mV}/^\circ\text{C}$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. \*1: The temperature must be controlled  $25^\circ\text{C}$  for  $V_F$  measurement.  $V_F$  value measured at other temperature must be adjusted to  $V_F (25^\circ\text{C})$

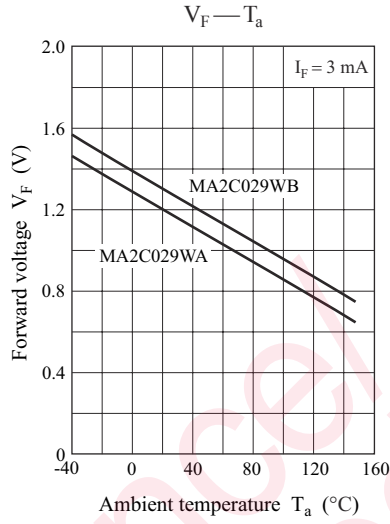
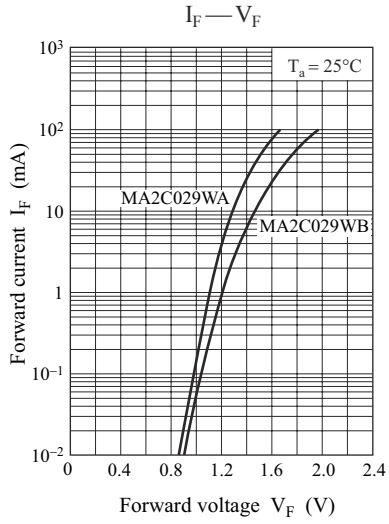
\*2:

Type	$V_F (V)$
MA2C029WA	1.18 to 1.28
MA2C029WB	1.26 to 1.36

\*3:  $T_j = 25^\circ\text{C}$  to  $150^\circ\text{C}$

### ■ Cathode Indication

Type No.	MA2C029WA	MA2C029WB
Color	Light blue	Brown



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